5 é / Descriptions

9 5 : .> / / x J· 6 4 6 â o Silicon PNP Digital transistor in a SOT-23 Plastic Package.

¤ ª / Features

˜ x å k ¿ Ł k ×5 « ^ y ò- v i k)í D }o

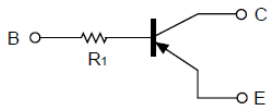
With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process,HF Product.

Đ ÷ / Applications

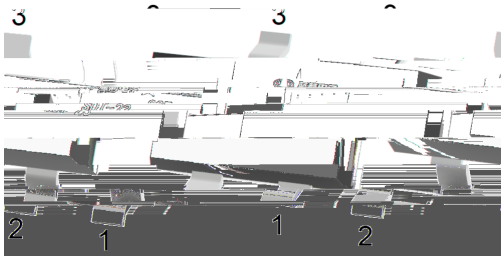
9 ...o F , Łо µ Ł Y C Ü Ł o

Switching, inverter circuit, interface circuit and driver circuit applications.

Ã W] Ô · / Equivalent Circuit



• Û - æ / Pinning



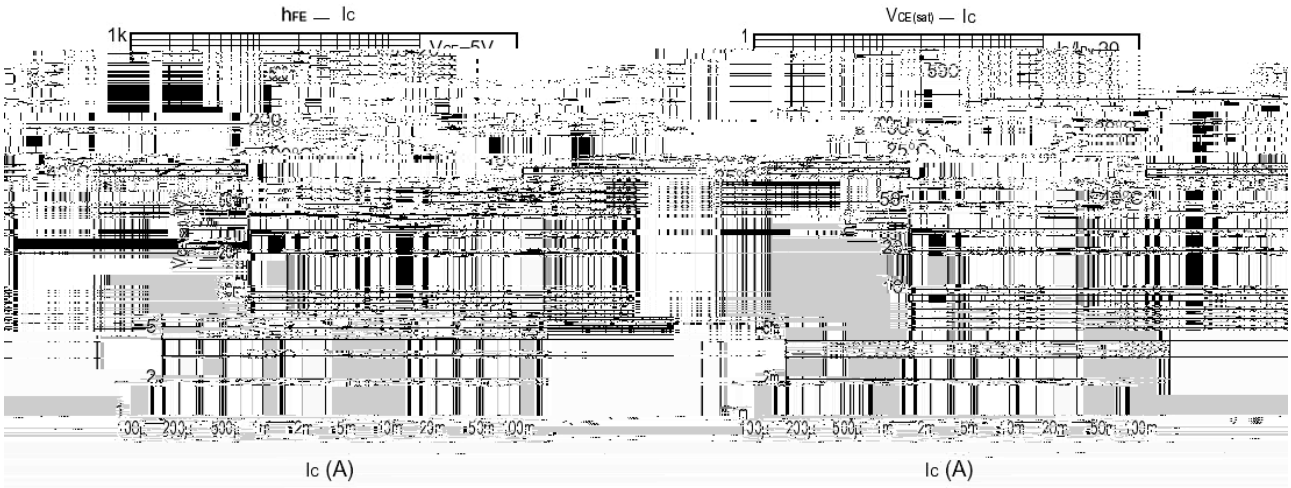
PIN 1 y Base PIN 2 y Emitter PIN 3 y Collector

Z Ü B , M V / h_{FE} Classifications & Marking

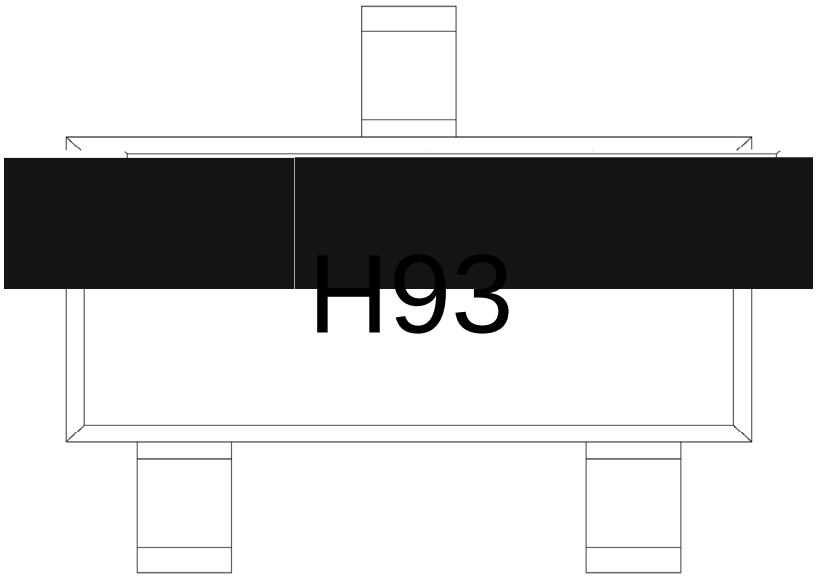
Marking	H93

@ Parameter	Z Symbol	 Rating	% y Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V_{CEO}	-50	V
Emitter-Base Voltage	V_{EBO}	-5	V
Collector Current	I_C	-100	mA

Ô ? d • Ž ¢ / Electrical Characteristic Curve



, M y ƒ / Marking Instructions



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. y , [W A

93 y ” Z W A

Note:

. y Company Code

93 y Product Type Code

š WD t … • Ž ¢ **(** x / **)** **/** : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

“ ¢ y	Note:
1o ˜ ‰ 150 ‰180 - k 60 ‰90sec;	1.Preheating:150~180 - , Time:60~90sec.
2o Q 245 r 5 - k 4 Ò 5 r 0.5sec;	2.Peak Temp.:245 r 5 - , Duration:5 r 0.5sec.
3o D N òi Ò0 , 2 ‰10 - /sec.	3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

y 260 r 5 - y 10 r 1 sec. Temp.:260±5 Time:10±1 sec

G P á / Packaging SPEC.

2 & x / REEL

Package Type 7>û ˜ E	Units ;>û ¦H	Dimension ;>û p . (unit Æmm³)